

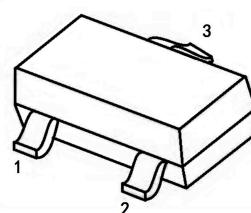
KY3401

-30V P-Channel Mosfet

FEATURES

- $R_{DS(ON)} \leq 55m\Omega$ (45m Ω Typ.) @ $V_{GS}=-10V$
- $R_{DS(ON)} \leq 68m\Omega$ (53m Ω Typ.) @ $V_{GS}=-4.5V$
- $R_{DS(ON)} \leq 96m\Omega$ (72m Ω Typ.) @ $V_{GS}=-2.5V$

SOT-23

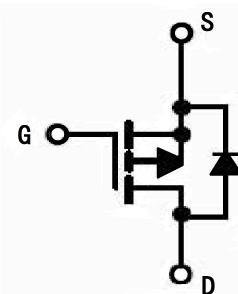


1. GATE
2. SOURCE
3. DRAIN

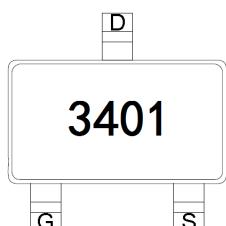
APPLICATIONS

- PWM Applications
- Load Switch
- Power Management

P-CHANNEL MOSFET



MARKING



Other marks: "R1" or "A19T"

MAXIMUM RATINGS ($T_a=25^\circ C$ unless otherwise noted)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		-30	V
V_{GSS}	Gate-Source Voltage		± 12	V
I_D	Continuous Drain Current	$T_a = 25^\circ C$	-4.2	A
		$T_a = 100^\circ C$	-2.7	A
I_{DM}	Pulsed Drain Current ^{note1}		-30	A
P_D	Power Dissipation $T_a = 25^\circ C$		1.5	W
R_{eJA}	Thermal Resistance, Junction to Ambient		83	°C/W
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	°C



MOSFET ELECTRICAL CHARACTERISTICS Ta=25 °C unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D = -250μA	-30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -30V, V _{GS} = 0V	-	-	-1	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±12V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D =-250μA	-0.6	-0.9	-1.3	V
R _{D(on)}	Static Drain-Source on-Resistance ^{note2}	V _{GS} =-10V, I _D =-4A	-	45	55	mΩ
		V _{GS} =-4.5V, I _D =-3A	-	53	68	
		V _{GS} =-2.5V, I _D =-1A	-	72	96	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} = -15V, V _{GS} = 0V f = 1.0MHz	-	880	-	pF
C _{oss}	Output Capacitance		-	105	-	pF
C _{rss}	Reverse Transfer Capacitance		-	65	-	pF
Q _g	Total Gate Charge	V _{DS} = -15V, I _D = -4.2A V _{GS} = -10V	-	8.5	-	nC
Q _{gs}	Gate-Source Charge		-	1.8	-	nC
Q _{gd}	Gate-Drain("Miller") Charge		-	2.7	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} = -15V, I _D = -1A, V _{GS} =-10V, R _{GEN} =2.5Ω	-	7	-	ns
t _r	Turn-on Rise Time		-	3	-	ns
t _{d(off)}	Turn-off Delay Time		-	20	-	ns
t _f	Turn-off Fall Time		-	12	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-4.2	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-30	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = -4.2A	-	-0.8	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

TYPICAL PERFORMANCE CHARACTERISTICS

Figure1: Output Characteristics

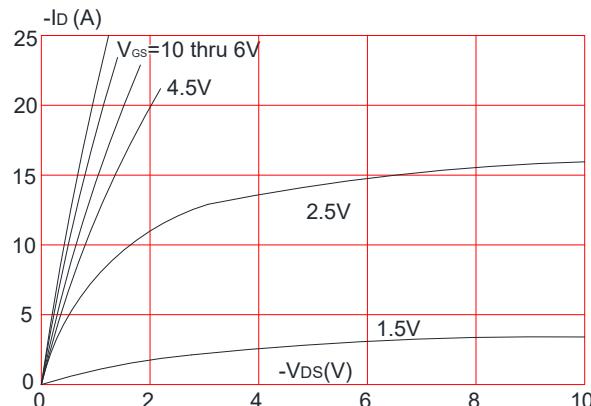


Figure 2: Typical Transfer Characteristics

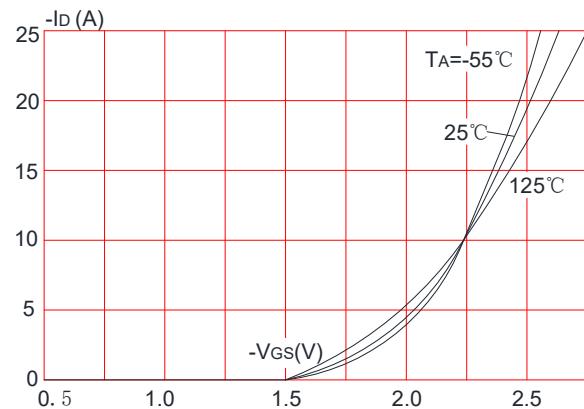


Figure 3: On-resistance vs. Drain Current

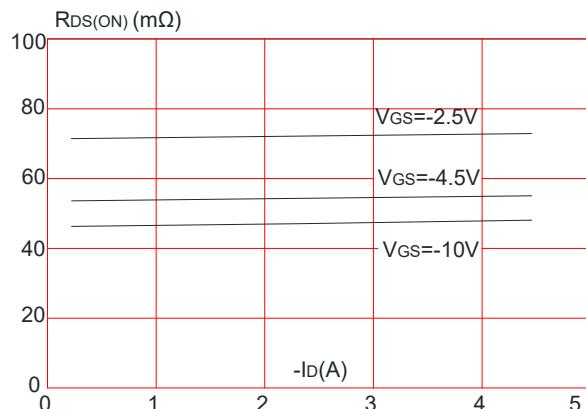


Figure 5: Gate Charge Characteristics

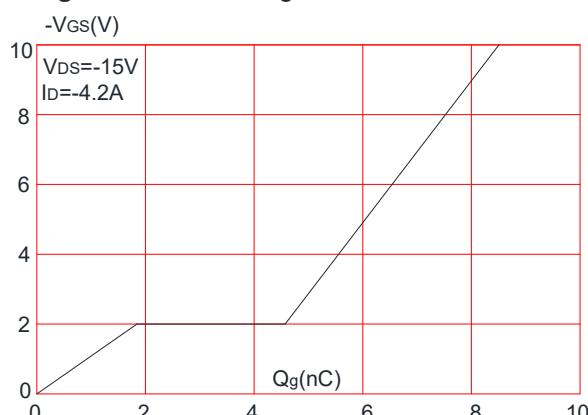


Figure 4: Body Diode Characteristics

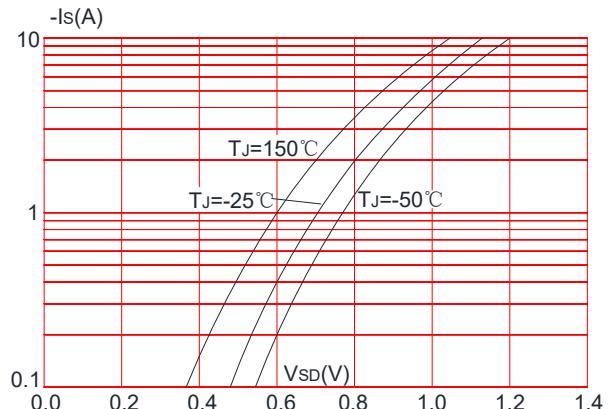
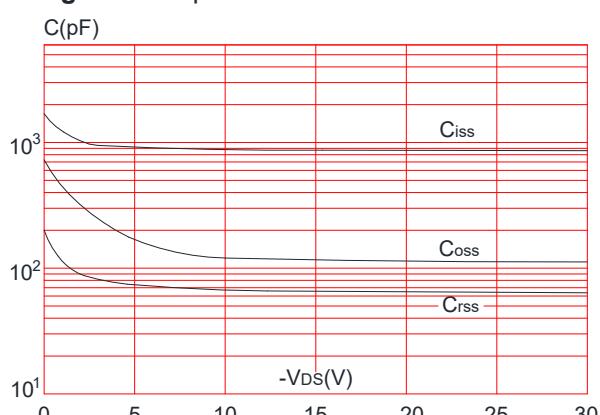


Figure 6: Capacitance Characteristics



TYPICAL PERFORMANCE CHARACTERISTICS (cont.)

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

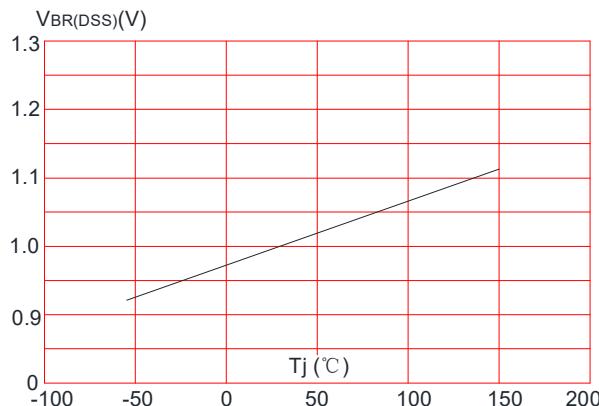


Figure 8: Normalized on Resistance vs. Junction Temperature

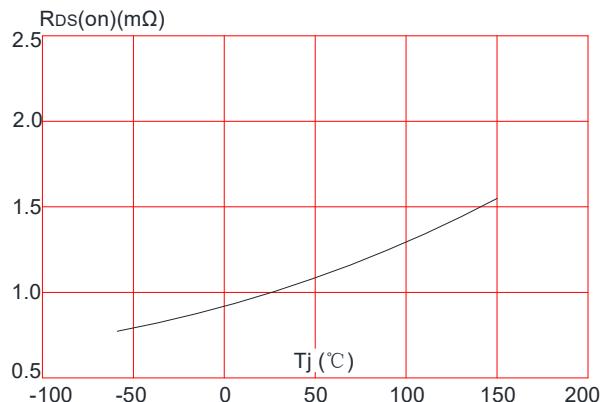


Figure 9: Maximum Safe Operating Area

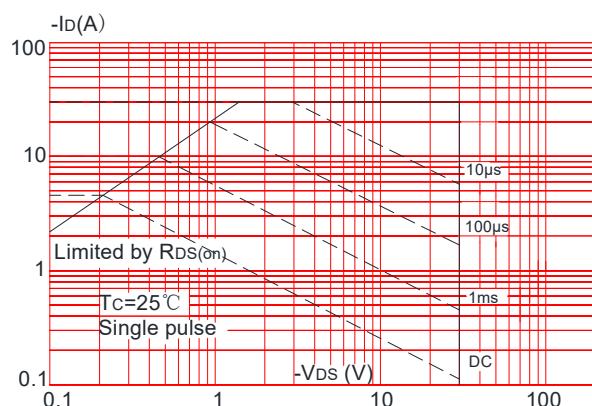


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

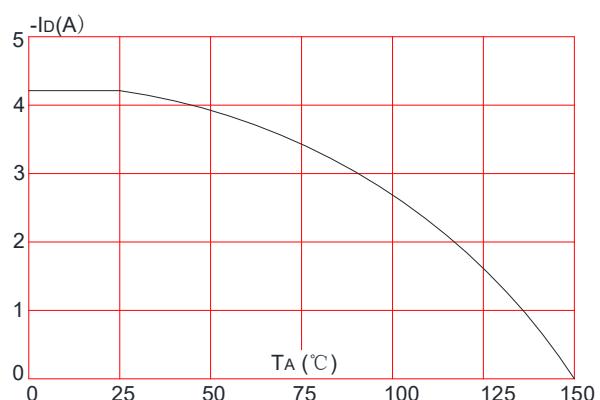
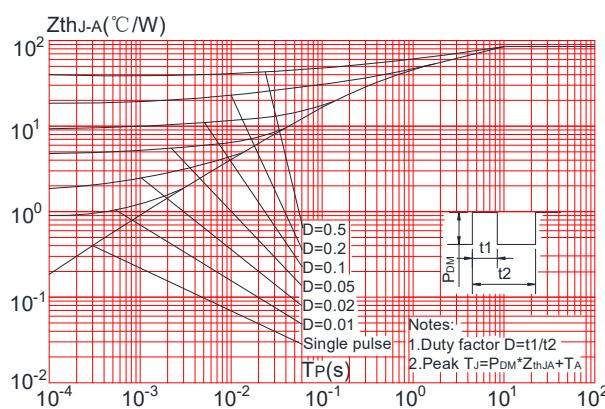
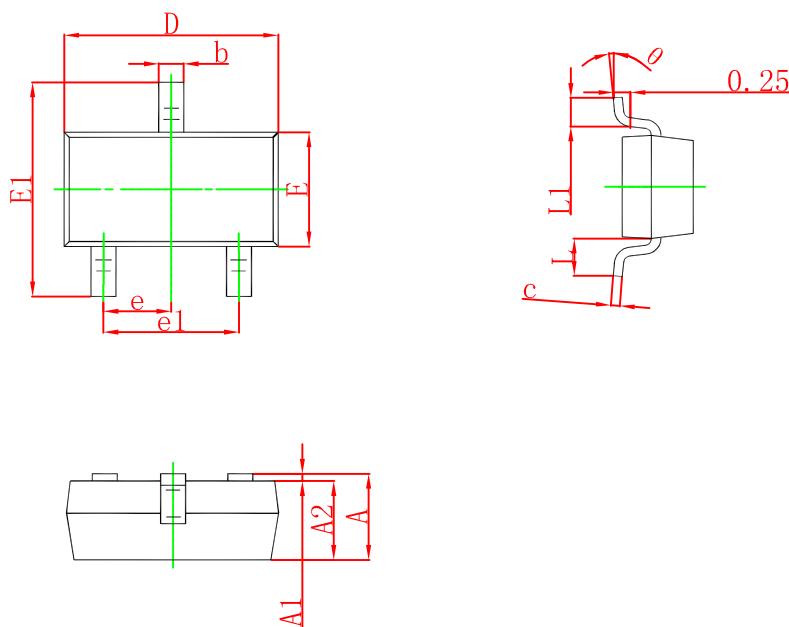


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



SOT-23 PACKAGE OUTLINE DRAWING



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°